

Epoxy Technology EPO-TEK® H20E-175 Electrically Conductive, Silver Epoxy

Category : Polymer , Thermoset , Epoxy , Epoxy, Electrically Conductive

Material Notes:

Product Description: EPO-TEK® H20E-175 is a two component epoxy designed for semiconductor die-attach. It is a higher Tg version of EPO-TEK® H20E. It was designed to be used in semiconductor / JEDEC packaging, microelectronic packaging of hybrids, as well as high temperature devices and assembly.
Advantages & Application Notes: Thixotropic paste-like rheology allows for high speed dispensing and screen printing operations. It can also be applied by hand techniques using spatula, toothpick, or stamping chuck. Suggested for Rf/Microwave device packaging found in military, commercial, aerospace and cockpit, and industrial (down-hole petrochemical) circuits. > 3 day pot-life allows for mass production yielding low waste. Information Provided by Epoxy Technology

Order this product through the following link:

http://www.lookpolymers.com/polymer_Epoxy-Technology-EPO-TEK-H20E-175-Electrically-Conductive-Silver-Epoxy.php

Physical Properties	Metric	English	Comments
Specific Gravity	3.07 g/cc	3.07 g/cc	Part B
	3.44 g/cc	3.44 g/cc	Part A
Viscosity	2800 - 3800 cP	2800 - 3800 cP	100 rpm
	@Temperature 23.0 °C	@Temperature 73.4 °F	

Mechanical Properties	Metric	English	Comments
Hardness, Shore D	70	70	
Tensile Modulus	4.33 GPa	628 ksi	Storage
Shear Strength	8.908 MPa	1292 psi	Lap
	>= 23.4 MPa	>= 3400 psi	Die

Thermal Properties	Metric	English	Comments
CTE, linear	20.0 µm/m-°C	11.1 µin/in-°F	Below Tg
	88.0 µm/m-°C	48.9 µin/in-°F	Above Tg
Thermal Conductivity	2.04 W/m-K	14.2 BTU-in/hr-ft ² -°F	
Maximum Service Temperature, Air	250 °C	482 °F	Continuous
	350 °C	662 °F	Intermittent
Minimum Service Temperature, Air	-55.0 °C	-67.0 °F	Continuous
	-55.0 °C	-67.0 °F	Intermittent
	>= 80.0 °C	>= 176 °F	Dynamic Cure 20–250°C /ISO 25 Min;

Thermal Properties	Metric	English	Comments
Decomposition Temperature	450 °C	842 °F	Degradation Temperature

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.00040 ohm-cm	<= 0.00040 ohm-cm	

Processing Properties	Metric	English	Comments
Cure Time	60.0 min	1.00 hour	
	@Temperature 180 °C	@Temperature 356 °F	
	120 min	2.00 hour	
	@Temperature 150 °C	@Temperature 302 °F	
Pot Life	5040 min	5040 min	
Shelf Life	12.0 Month	12.0 Month	
	@Temperature 25.0 °C	@Temperature 77.0 °F	

Descriptive Properties	Value	Comments
Color	Silver	Part A
	Silver	Part B
Consistency	Smooth thixotropic paste	
Mix Ratio By Weight	1:1	
Number of Components	Two	
Thixotropic Index	3.1	
Weight Loss	0.05%	200°C
	0.11%	250°C
	0.25%	300°C

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